

Environmental testing - Part 3-13: Supporting
documentation and guidance on Test T - Soldering

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

See Eesti standard EVS-EN 60068-3-13:2016 sisaldab Euroopa standardi EN 60068-3-13:2016 ingliskeelset teksti.	This Estonian standard EVS-EN 60068-3-13:2016 consists of the English text of the European standard EN 60068-3-13:2016.
Standard on jõustunud sellekohase teate avaldamisega EVS Teatajas.	This standard has been endorsed with a notification published in the official bulletin of the Estonian Centre for Standardisation.
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English Version

**Environmental testing - Part 3-13: Supporting documentation
and guidance on Test T - Soldering
(IEC 60068-3-13:2016)**

Essais d'environnement - Partie 3-13: Documentation
d'accompagnement et guide sur les essais T - Brasage
(IEC 60068-3-13:2016)

Umweltprüfungen - Teil 3-13: Ergänzende Unterlagen und
Anleitung zur Prüfung T: Löten
(IEC 60068-3-13:2016)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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European foreword

The text of document 91/1345/FDIS, future edition 1 of IEC 60068-3-13, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60068-3-13:2016.

The following dates are fixed:

- latest date by which the document has to be (dop) 2017-03-17
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publication of an identical national
standard or by endorsement
- latest date by which the national (dow) 2019-06-17
standards conflicting with the
document have to be withdrawn

This document supersedes EN 60068-2-44:1995.

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Endorsement notice

The text of the International Standard IEC 60068-3-13:2016 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2 Series	NOTE	Harmonized as EN 60068-2 Series.
IEC 60749-20	NOTE	Harmonized as EN 60749-20.
IEC 61190-1-1	NOTE	Harmonized as EN 61190-1-1.
IEC 61191 Series	NOTE	Harmonized as EN 61191 Series.
IEC 61192 Series	NOTE	Harmonized as EN 61192 Series.
IEC 61760-4	NOTE	Harmonized as EN 61760-4.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-20	2008	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	2008
IEC 60068-2-58	-	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	-
IEC 60068-2-69	-	Environmental testing - Part 2: Tests - Test Te: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method	EN 60068-2-69	-
IEC 60068-2-83	-	Environmental testing - Part 2-83: Tests - Test Tf: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method using solder paste	EN 60068-2-83	-
IEC 61760-1	-	Surface mounting technology - Part 1: Standard method for the specification of surface mounting components (SMDs)	EN 61760-1	-
IEC 62137-3	-	Electronics assembly technology - Part 3: Selection guidance of environmental and endurance test methods for solder joints	EN 62137-3	-

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